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PATIENT NUMBER

U.S. **UTILITY** Patent Application

O.I.P.E.
SCANNED IK 2 Q.A.

PATENT DATE

APPLICATION NO. 09/898601 D CLASS SUBCLASS ARTUNIT F782 DAV TS

Eric Austin Steve Majgier David Padgett Kyle Springer

Apparatus and method for vacuum encapsulation of semiconductor chip packages

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TERMINAL		DRAWINGS		CLAIMS ALLOWED			
DISCLAIMER	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.		
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